

ABSTRACT

ADHESIVE TAPE FOR SEMICONDUCTOR PROCESSING, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

The pressure sensitive adhesive tape for semiconductor processing according to the present invention is a pressure sensitive adhesive tape including a base having a Young's modulus of 1000 MPa or more at 23°C, and a pressure sensitive adhesive layer provided on at least one surface of the base, and the product $(N) \times (C)$ of (N) and (C) is 500 or more at 30°C, and 9000 or less at 60°C, where (N) [μm] is a thickness of the pressure sensitive adhesive layer and (C) [μm] is a creep amount.

(No Fig.)